

IN THE CLAIMS:

Claims 1 through 18, 20, 24, 26, 28 and 32 were previously cancelled. None of the claims have been amended herein. All of the pending claims are presented below only for the convenience of the Examiner. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as previously amended.

1.-18. (Cancelled)

19. (Previously presented) A method of fabricating a multi-die assembly, comprising:  
providing a substrate including a plurality of conductors;  
attaching at least one active face-down base die to the substrate in electrical communication with  
at least some of the plurality of conductors;  
providing a layer of epoxy adhesive to a back side of the at least one base die;  
placing a back side of at least one active face-up stack die on the layer of epoxy adhesive;  
curing the layer of epoxy adhesive and securing the back side of at least one stack die to the at  
least one base die;  
providing a direct electrical path between the at least one stack die and at least one of the  
plurality of conductors;  
securing at least another stack die to the assembly including securing the at least another stack  
die to the at least one stack die;  
electrically connecting the at least another stack die and at least one of the plurality of substrate  
conductors;  
securing at least one discrete component to at least one of the at least one stack die and the at  
least one base die; and  
extending a die-to-component bond wire between the at least another stack die and the at least  
one discrete component.

20. (Cancelled)

21. (Previously presented) The method of claim 19, further comprising:  
securing at least one other discrete component to at least one of the at least one stack die, the at least one base die, and the substrate;  
electrically connecting the at least one other discrete component to at least one of the base die and the substrate; and  
extending a die-to-component bond wire between the at least one stack die and the at least one other discrete component.

22. (Previously presented) The method of claim 21, further comprising:  
extending a component-to-substrate bond wire between the at least one discrete component and at least one of the plurality of substrate conductors.

23. (Previously presented) The method of claim 19, wherein providing a layer of epoxy adhesive to a back side of the at least one base die includes providing a layer of electrically conductive adhesive to the back side of the at least one base die.

24. (Cancelled)

25. (Previously presented) The method of claim 23, further comprising electrically grounding the at least one base die via the layer of electrically conductive epoxy adhesive and the at least one stack die.

26. (Cancelled)

27. (Previously presented) The method of claim 19, further comprising:  
securing at least one other discrete component to the at least one stack die; and  
extending a component-to-substrate bond wire between the at least one other discrete component  
and at least one of the plurality of substrate conductors.

28. (Cancelled)

29. (Previously presented) The method of claim 19, further comprising:  
securing at least one other discrete component to the at least one base die; and  
extending a component-to-substrate bond wire between the at least one other discrete component  
and at least one of the plurality of substrate conductors.

30. (Previously presented) The method of claim 19, wherein the attaching at least one  
active face-down base die includes attaching at least two active face-down base dice to the  
substrate and electrically coupling each of the at least two active face-down base dice with at  
least one of the plurality of substrate conductors.

31. (Previously presented) The method of claim 30, further comprising bridging the  
at least one stack die between the at least two active face-down base dice.

32. (Cancelled)

33. (Previously presented) The method of claim 19, further comprising:  
securing at least one other discrete component to the substrate; and  
extending a die-to-component bond wire between the at least one stack die and the at least one  
other discrete component.

34. (Previously presented) The method of claim 33, further comprising extending a component-to-substrate bond wire between the at least one other discrete component and at least one of the plurality of substrate conductors.